

# Encapsulation



Encapsulation protects electronic components, connections or terminations from moisture and dirt, oil or other chemicals in the environment by completely encasing and sealing them with either a single- or plural-component resin. Resins may include epoxies, silicones or urethanes. Encapsulation can be accomplished at atmospheric pressure or under vacuum pressure when voids within the resin are undesirable.

Typical products that might be encapsulated include cable splice, coils, power supplies, sensors, switches, and control modules.

## For single-component resins

[Graco 1052](#) - for shot sizes under 2.5 cc's

[Graco 1092](#) - for shot sizes under 14 cc's

[Graco 1095](#) - for shot sizes under 40 cc's

Graco single-component Posiload pumps - for shot sizes beyond 40 cc's

## For two-component resins

[Graco PD44](#) - for shot sizes under 5 cc's.

[Graco PR70](#) - for shot sizes between 2 and 70 ccs's

[Graco HFR Metering System](#) - for shot sizes beyond 70 cc's

## Vacuum encapsulation

Feed systems (tanks) for all products mentioned can be configured as vacuum ready. Vacuum chambers can be integrated with any of the Graco products listed above by contacting Graco's Project Engineering group.